

IN THE CLAIMS

Please amend the following claims:

Claims 1-7 (cancelled)

8. (currently amended) An apparatus ~~A heat spreader for an IC circuit package,~~
comprising:
 an IC die;
 a thermal interface material comprising an inorganic material in direct contact
 with the IC die; and
 a thermally conductive heat spreader body coated with an organic surface
 protectant in direct contact with the thermal interface material. ~~having a first surface~~
 ~~thermally coupled to an IC die; and~~
 ~~a coating of organic surface protectant on the first surface and wherein the coating~~
 ~~directly abuts the IC die.~~
9. (currently amended) The apparatus of ~~A heat spreader as claimed in claim 8,~~ wherein
the heat spreader body comprises copper.
10. (currently amended) The apparatus of ~~A heat spreader as claimed in claim 8,~~ wherein
the organic surface protectant comprises one or more imidazole compounds.
11. (currently amended) The apparatus of ~~A heat spreader as claimed in claim 8,~~ wherein
the organic surface protectant comprises one or more triazole compounds or salts thereof.
12. (original) A heat spreader as claimed in claim 8, wherein the coating completely
envelops the body.

13. (currently amended) An IC package, comprising:
a package substrate;
an IC die attached to the substrate;
a thermal interface material comprising an inorganic material in direct contact with the IC die; and
a thermally conductive heat spreader body coated with an organic surface protectant in direct contact with the thermal interface material.
~~a heat spreader body having a first surface thermally coupled to the IC die; and~~
~~a coating of organic surface protectant disposed on the first surface and wherein the coating directly abuts the IC die.~~
14. (original) An IC package as claimed in claim 13, wherein the coating completely envelops the body.
15. (cancelled)
16. (currently amended) An IC package according to claim ~~[[15]]~~ 13, wherein the thermal interface material is a solder or solder-polymer hybrid.
17. (original) An IC package according to claim 13, wherein the body comprises copper.
18. (original) An IC package according to claim 13, wherein the organic surface protectant comprises one or more triazole compounds or salts thereof.
19. (previously presented) An IC package according to claim 13, wherein the first surface is coated with a metal.
20. (currently amended) A printed circuit board assembly comprising:
a printed circuit board,
an IC die electronically coupled to the printed circuit board~~[[, and]]~~

a thermal interface material comprising an inorganic material in direct contact with the IC die; and

a thermally conductive heat spreader body coated with an organic surface protectant in direct contact with the thermal interface material.

~~a heat spreader body having a first surface thermally coupled to the IC die; and
a coating of organic surface protectant disposed on the first surface and wherein the coating directly abuts the IC die.~~

21. (currently amended) A printed circuit board assembly as claimed in claim 20, ~~further comprising a thermal interface material between the IC die and the coated first surface of the heat spreader,~~ wherein the thermal interface material is a solder or solder-polymer hybrid.

22. (original) A printed circuit board assembly as claimed in claim 20, wherein the IC die is directly attached to the printed circuit board.

23. (original) A printed circuit board assembly as claimed in claim 20, wherein the IC die is attached to a package substrate that is attached to the printed circuit board.